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AMENDMENTS TO SPECIFICATION

- In the Specification please amend the paragraph starting on page 3, line 15, as follows:

Referring now to FIG. 2, therein is shown a side view of the system 10 in accordance with the present invention. The semiconductor wafer 14 is shown mounted on a rotating wafer holder 26, which rotates in the direction indicated by the arrow 22. A thermally conducting non-stick surface 28 is shown under the top plate 16 in contact with the semiconductor wafer 14. As the top plate 16 rotates in the direction indicated by the arrow 20, it traverses the semiconductor wafer 14 along the horizontal plane in the direction indicated by a pair of arrows 30[.]. whereby a low dielectric constant (low-k) ILD layer on the semiconductor wafer 14 is stretched to give rise to a linear molecular arrangement. The linear molecular arrangement in the ILD layer improves its physical characteristics; e.g., mechanical strength and for conducting polymers, lower resistivity.

- In the Specification please amend the paragraph starting on page 4, line 13, as follows:

Referring now to FIG. 4, therein is shown a side view of the system 50 in accordance with the present invention. The wafer 54 is shown mounted on a rotating wafer holder 66, which rotates in the direction indicated by the arrow 62. The roller 56 has a ~~termally~~ thermally conducting non-stick surface 68, which rotates in contact with the semiconductor wafer 54. As the roller 56, which rotates about the axis 57, rotates in the direction indicated by the arrow 60, it laterally traverses along the horizontal plane in the direction indicated by the arrows 70[.]. whereby a low dielectric constant (low-k) ILD layer on the semiconductor wafer 14 is stretched to give rise to a linear molecular arrangement. The linear molecular arrangement in the ILD layer improves its physical characteristics; e.g., mechanical strength and for conducting polymers, lower resistivity.